

Title (en)
COMPONENT MODULE.

Title (de)
MODUL MIT KOMPONENTEN.

Title (fr)
MODULE A COMPOSANTS.

Publication
EP 0649590 A1 19950426 (EN)

Application
EP 93915044 A 19930602

Priority
• SE 9202077 A 19920706
• SE 9300486 W 19930602

Abstract (en)
[origin: WO9401987A1] The present invention relates to a component module (70) comprised by at least one internal or external carrier substrate, at least one circuit (71) with at least thereto belonging surrounding components or components (72). The circuit (71) is directly mounted to the carrier substrate and the component module (70) comprises an enclosing device and furthermore is so formed that it can be directly mounted onto an external carrier substrate and or a printed board externally having the form and dimensions of a standard circuit and the enclosing device at least in one direction essentially encapsulating the major part component module. The invention furthermore relates to a transceiver module per se forming component module.

IPC 1-7
H05K 7/00; H04B 10/14; G02B 6/42

IPC 8 full level
G02B 6/34 (2006.01); **G02B 6/42** (2006.01); **H01L 23/31** (2006.01); **H01L 23/498** (2006.01); **H01L 25/10** (2006.01); **H01L 25/18** (2006.01); **H04B 10/07** (2013.01); **H04B 10/40** (2013.01); **H04B 10/43** (2013.01); **H04B 10/50** (2013.01); **H04B 10/60** (2013.01); **H05K 1/14** (2006.01); **H05K 7/20** (2006.01); **H05K 1/02** (2006.01); **H05K 3/28** (2006.01); **H05K 3/34** (2006.01); **H05K 3/36** (2006.01); **H05K 3/42** (2006.01)

CPC (source: EP KR)
G02B 6/4201 (2013.01 - EP); **G02B 6/424** (2013.01 - EP); **G02B 6/4245** (2013.01 - EP); **G02B 6/4246** (2013.01 - EP); **G02B 6/428** (2013.01 - EP); **G02B 6/4285** (2013.01 - EP); **H01L 23/3157** (2013.01 - EP); **H01L 23/49838** (2013.01 - EP); **H05K 1/141** (2013.01 - EP); **H05K 7/00** (2013.01 - KR); **G02B 6/4266** (2013.01 - EP); **G02B 6/4286** (2013.01 - EP); **H01L 24/45** (2013.01 - EP); **H01L 24/48** (2013.01 - EP); **H01L 24/49** (2013.01 - EP); **H01L 2224/05553** (2013.01 - EP); **H01L 2224/05554** (2013.01 - EP); **H01L 2224/45124** (2013.01 - EP); **H01L 2224/48091** (2013.01 - EP); **H01L 2224/48227** (2013.01 - EP); **H01L 2224/49171** (2013.01 - EP); **H01L 2924/00014** (2013.01 - EP); **H01L 2924/01014** (2013.01 - EP); **H01L 2924/01019** (2013.01 - EP); **H01L 2924/01057** (2013.01 - EP); **H01L 2924/12041** (2013.01 - EP); **H01L 2924/14** (2013.01 - EP); **H01L 2924/19041** (2013.01 - EP); **H01L 2924/19105** (2013.01 - EP); **H01L 2924/30107** (2013.01 - EP); **H01L 2924/3011** (2013.01 - EP); **H01L 2924/3025** (2013.01 - EP); **H05K 1/0206** (2013.01 - EP); **H05K 1/0231** (2013.01 - EP); **H05K 1/0237** (2013.01 - EP); **H05K 3/284** (2013.01 - EP); **H05K 3/3442** (2013.01 - EP); **H05K 3/368** (2013.01 - EP); **H05K 3/429** (2013.01 - EP)

Citation (search report)
See references of WO 9401987A1

Designated contracting state (EPC)
CH DE DK ES FR GB GR IE IT LI NL SE

DOCDB simple family (publication)
WO 9401987 A1 19940120; AU 4517193 A 19940131; AU 4681697 A 19980205; BR 9306685 A 19981208; CN 1041479 C 19981230; CN 1081297 A 19940126; EP 0649590 A1 19950426; FI 950058 A0 19950105; FI 950058 A 19950105; JP H08501657 A 19960220; KR 950702790 A 19950729; MX PA93003941 A 20101112; NO 950038 D0 19950105; NO 950038 L 19950105; SE 9202077 D0 19920706; SE 9202077 L 19940107

DOCDB simple family (application)
SE 9300486 W 19930602; AU 4517193 A 19930602; AU 4681697 A 19971201; BR 9306685 A 19930602; CN 93108141 A 19930705; EP 93915044 A 19930602; FI 950058 A 19950105; JP 50320893 A 19930602; KR 19950700054 A 19950106; MX 9303941 A 19930630; NO 950038 A 19950105; SE 9202077 A 19920706